



**THE DATASHEET OF
MBRS260T3G**



MBRS260T3G, NRVBS260T3G

Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Over-Voltage Protection
- Low Forward Voltage Drop
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These are Pb-Free Devices

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings:
 - ◆ Machine Model = C
 - ◆ Human Body Model = 3B



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SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 60 VOLTS



SMB
CASE 403A

MARKING DIAGRAM



B26 = Specific Device Code
A = Assembly Location**
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------------------------------------------|------------------|------------------------|
| MBRS260T3G, NRVBS260T3G*, NRVBS260T3G-VF01* | SMB (Pb-Free) | 2,500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|-------------------------------------------------------------------------------------------------------------|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 60 | V |
| Average Rectified Forward Current (At Rated V_R , $T_L = 95^\circ\text{C}$) | I_O | 2.0 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 60 | A |
| Storage Temperature Range | T_{stg} | -55 to +150 | $^\circ\text{C}$ |
| Operating Junction Temperature | T_J | -55 to +125 | $^\circ\text{C}$ |
| Voltage Rate of Change (Rated V_R , $T_J = 25^\circ\text{C}$) | dv/dt | 10,000 | V/ μs |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--------------------------------------------------|-----------------|-------|---------------------------|
| Thermal Resistance, Junction-to-Lead (Note 1) | $R_{\theta JL}$ | 24 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 80 | |

- Mounted with minimum recommended pad size, PC Board FR4.
- 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | | Unit |
|------------------------------------------------------------------------------------------------------------|--------|--------------------------|---------------------------|------|
| | | $T_J = 25^\circ\text{C}$ | $T_J = 125^\circ\text{C}$ | |
| Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 1.0\text{ A}$) ($i_F = 2.0\text{ A}$) | V_F | 0.51 | 0.475 | V |
| | | 0.63 | 0.55 | |
| Maximum Instantaneous Reverse Current (Note 3) ($V_R = 60\text{ V}$) | I_R | $T_J = 25^\circ\text{C}$ | $T_J = 125^\circ\text{C}$ | mA |
| | | 0.2 | 20 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Pulse Test: Pulse Width $\leq 250\ \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

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TYPICAL CHARACTERISTICS

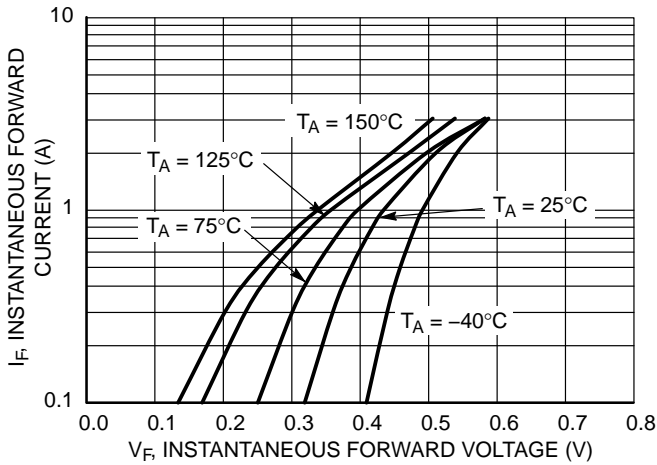


Figure 1. Typical Forward Voltage

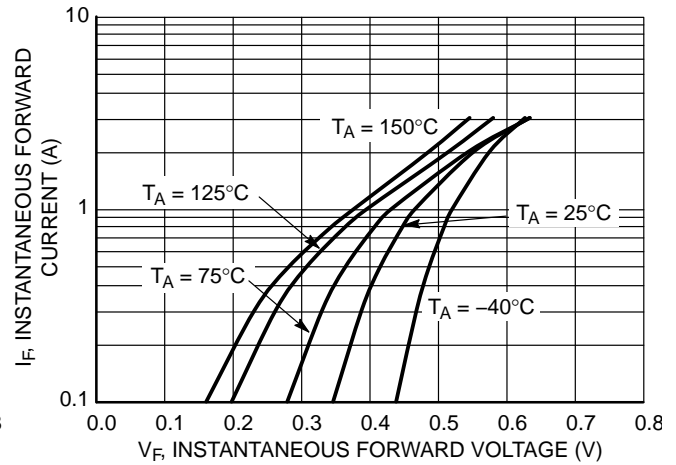


Figure 2. Maximum Forward Voltage

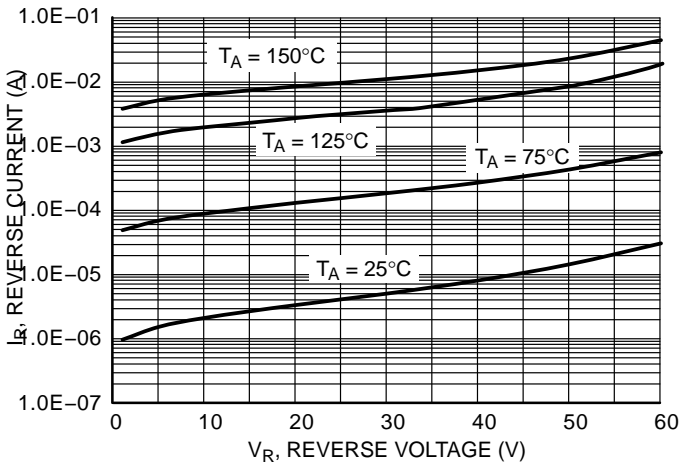


Figure 3. Typical Reverse Current

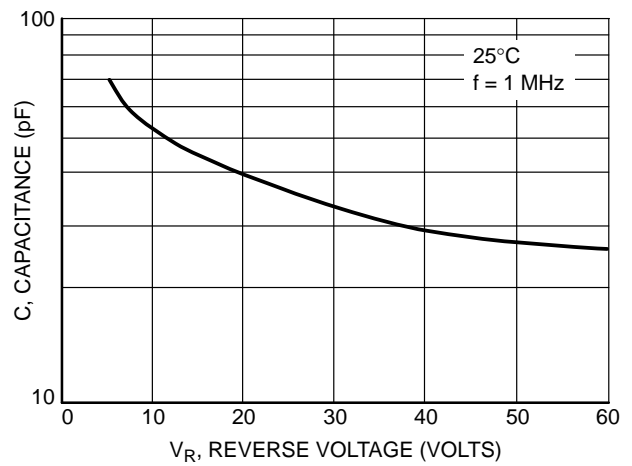


Figure 4. Typical Capacitance

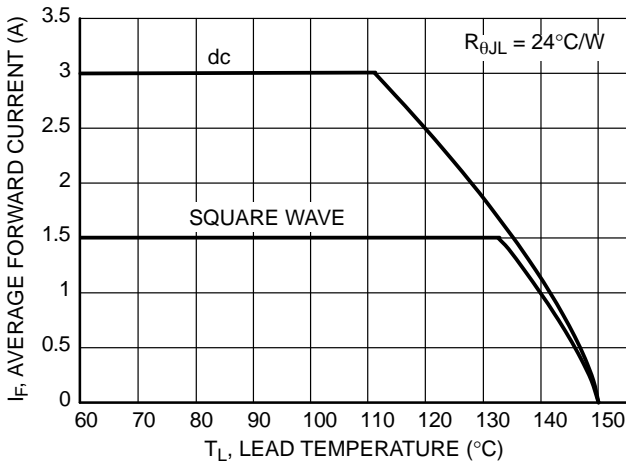


Figure 5. Current Derating – Junction to Lead

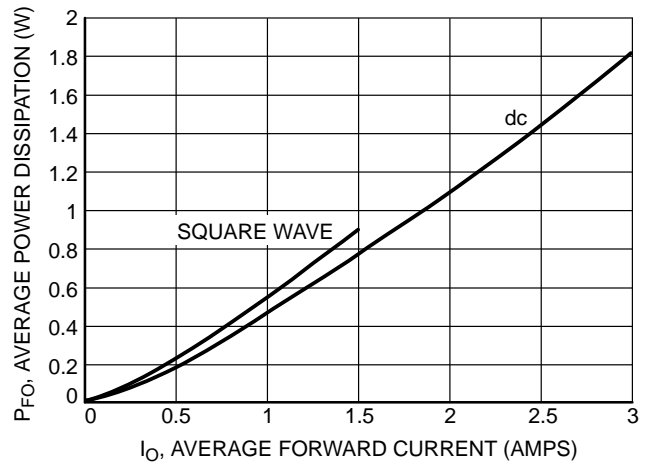


Figure 6. Forward Power Dissipation

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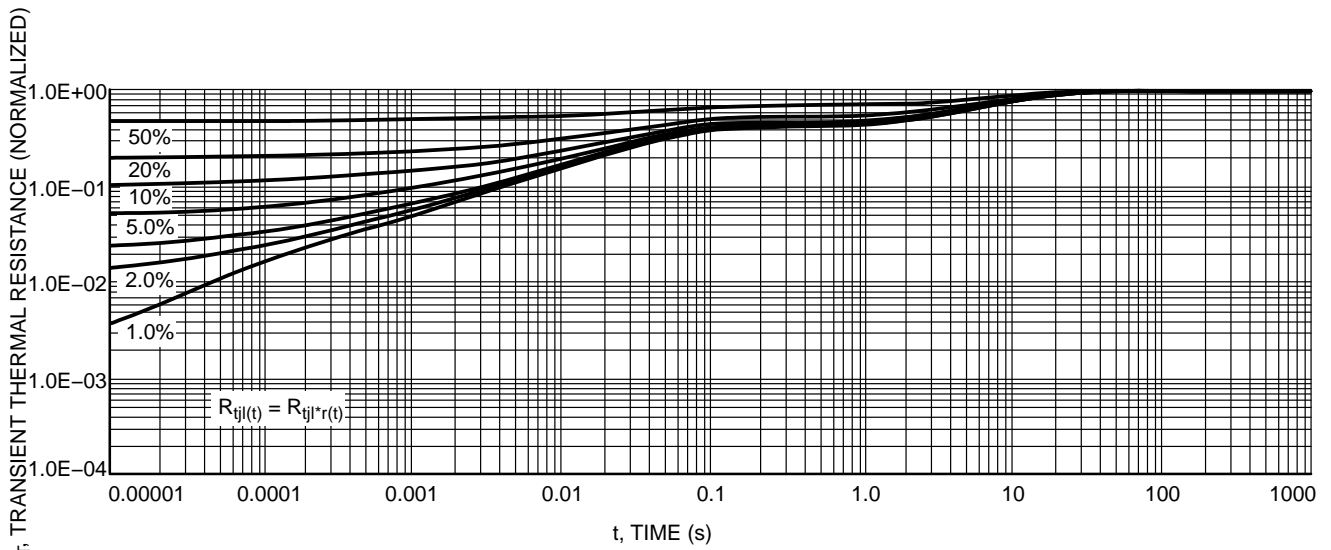


Figure 7. Thermal Response – Junction to Case

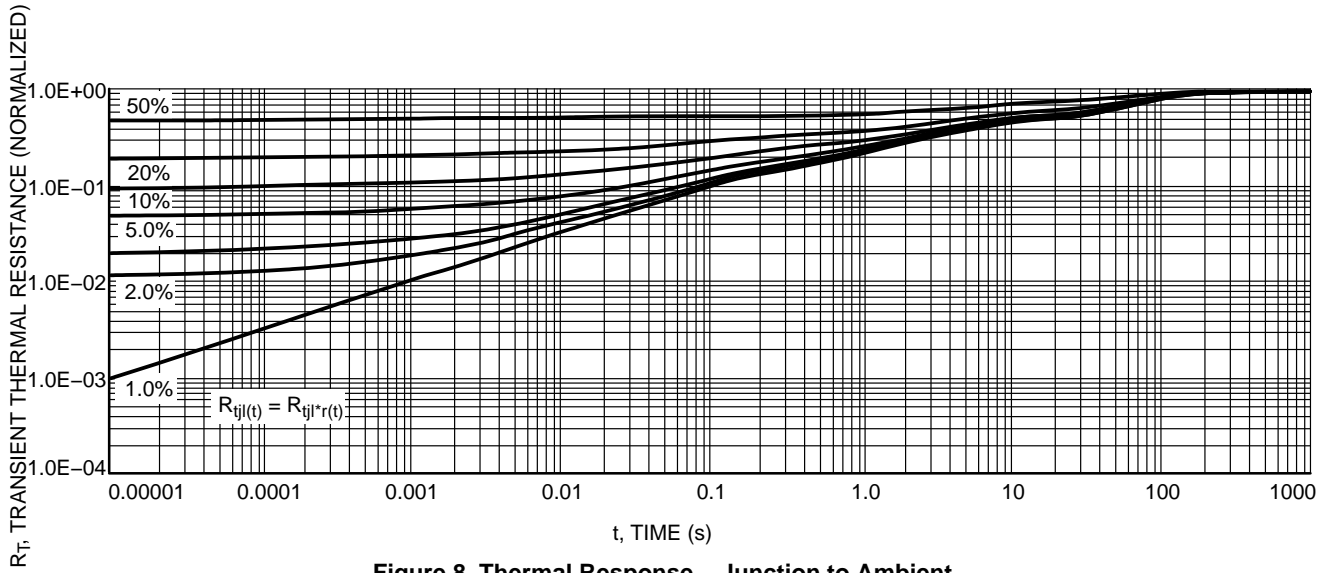
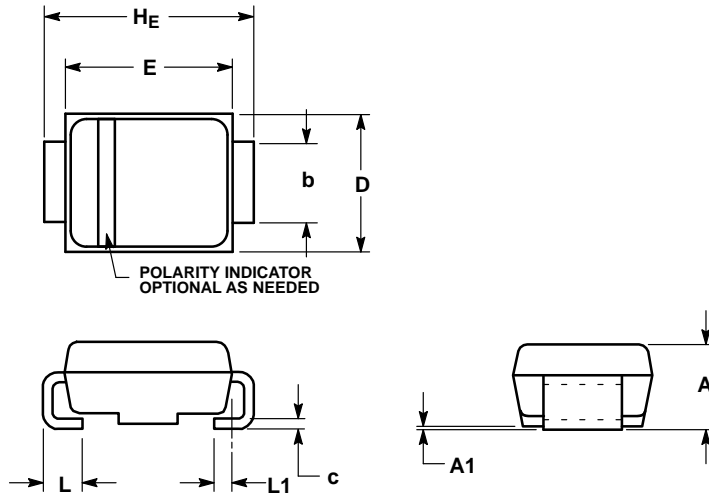


Figure 8. Thermal Response – Junction to Ambient

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PACKAGE DIMENSIONS

SMB
CASE 403A-03
ISSUE J

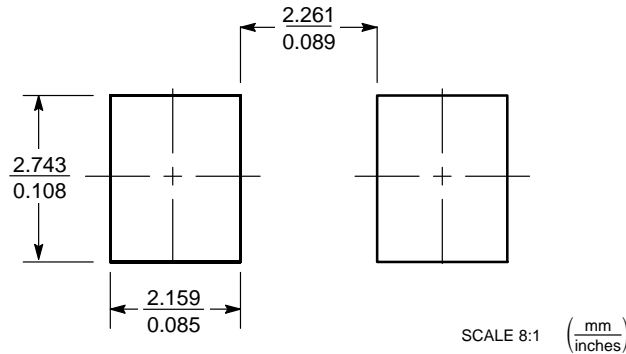


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.95 | 2.30 | 2.47 | 0.077 | 0.091 | 0.097 |
| A1 | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| b | 1.96 | 2.03 | 2.20 | 0.077 | 0.080 | 0.087 |
| c | 0.15 | 0.23 | 0.31 | 0.006 | 0.009 | 0.012 |
| D | 3.30 | 3.56 | 3.95 | 0.130 | 0.140 | 0.156 |
| E | 4.06 | 4.32 | 4.60 | 0.160 | 0.170 | 0.181 |
| HE | 5.21 | 5.44 | 5.60 | 0.205 | 0.214 | 0.220 |
| L | 0.76 | 1.02 | 1.60 | 0.030 | 0.040 | 0.063 |
| L1 | 0.51 REF | | | 0.020 REF | | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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